ABBOCIATION CONNECTING ELECTRONICS INDUSTRES® Material Compositio © Copyright 2005. IPC, Ba international and Pan-Ameri	nnockburn, Illinois. A	All rights reserved u ntions.	under both	This docume level parts, t	ent is a declar he declaration	ation of the s	ubstances es all lowe	within the manufacture relation of the manufacture relation of the materials for which we have a set of the manufacture of the	urer listed i which the n	tem. Note:	if the item is an as r has engineering	sembly with lower responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute			e *	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					als and Mfg Information			
Supplier Information													
Company name* Company unique ID			Unique IE			que ID Authority				Response Date*			
onsemi	nsemi				2				2023-06	2023-06-08			
ontact Name Title - Contact]	Phone - Contact*				Email -	Email - Contact*			
Product-Env-Stewards Product Enviro Compliance					NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Representative]	Phone - Representative*				Email - Representative*				
Product-Env-Stewards	Product Env	Product Enviro Compliance			NA				Produc	Product-Env-Stewards@onsemi.com			
Requester Item Number M	Ifr Item Number	Mfr Item Name	r Item Name		Effective Da	te Version	N	Manufacturing Site		Weight*	UOM	Unit Type	
F	DMF6704V	MF6704V DrMOS Module		2			1	TH6		91.293	mg	Each	
Manufacturing Proccess Information		1									I	I	
Terminal Plating / Grid Array Material	Terminal Base	Ferminal Base Alloy		L Rating	Peak Pro	k Process Body Temperature Max Time at Pe		Temperature Number of Reflow Cy		ber of Reflow Cyc	les		
Precious metal (e.g. Ag,Au, NiPdAu) Sn)	(no CU Alloy	1			260	260 C		30 sec		seconds 3			
Comments													
evel 1 - maximum time at peak temperature du	ring soldering is 10-3	30 seconds											
for more information regarding material compo	osition please refer to	o page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	4.351	mg	Supplier	Silicon (Si)	7440-21-3		4.351	mg
Die Attach	1.134	mg	Supplier	Silver (Ag)	7440-22-4		0.9809	mg
			Supplier	Phenolic Resin-2	54208-63-8		0.1531	mg
Lead Frame	47.356	mg	Supplier	Zinc (Zn)	7440-66-6		0.0591	mg
			Supplier	Iron (Fe)	7439-89-6		1.1129	mg
			Supplier	Copper (Cu)	7440-50-8		46.1452	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0388	mg
Mold Compound-Black	36.58	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		1.719	mg
			Supplier	Carbon Black (C)	1333-86-4		0.037	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		33.105	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1.719	mg
Plating	0.661	mg	Supplier	Silver (Ag)	7440-22-4		0.01	mg
			Supplier	Palladium (Pd)	7440-05-3		0.024	mg
			В	Nickel (Ni)	7440-02-0		0.614	mg
			Supplier	Gold (Au)	7440-57-5		0.013	mg
Wire Bond - Au	0.085	mg	Supplier	Gold (Au)	7440-57-5		0.085	mg
Wire Bond - Cu	1.126	mg	Supplier	Palladium (Pd)	7440-05-3		0.0231	mg
			Supplier	Copper (Cu)	7440-50-8		1.1029	mg